

## OptiMOS®-P Small-Signal-Transistor Feature

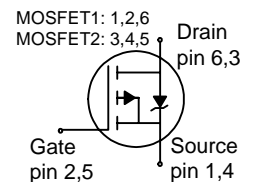
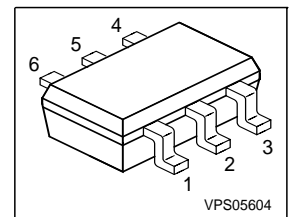
- Dual P-Channel
- Enhancement mode
- Super Logic Level (2.5 V rated)
- 150°C operating temperature
- Avalanche rated
- dv/dt rated
- Pb-free lead plating; RoHS compliant
- Qualified according to AEC Q101
- Halogen-free according to IEC61249-2-21



### Product Summary

$V_{DS}$	-20	V
$R_{DS(on)}$	1.2	$\Omega$
$I_D$	-0.39	A

PG-SOT-363



Type	Package	Tape & Reel	Marking
BSD 223P	PG-SOT-363	H6327: 3000pcs/r	X1s

### Maximum Ratings, at $T_j = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Value	Unit
Continuous drain current $T_A=25^\circ\text{C}$ $T_A=70^\circ\text{C}$	$I_D$	-0.39 -0.31	A
Pulsed drain current $T_A=25^\circ\text{C}$	$I_{D \text{ puls}}$	-1.56	
Avalanche energy, single pulse $I_D=-0.39 \text{ A}$ , $V_{DD}=-10\text{V}$ , $R_{GS}=25\Omega$	$E_{AS}$	1.4	mJ
Reverse diode dv/dt $I_S=-0.39\text{A}$ , $V_{DS}=-16\text{V}$ , $di/dt=200\text{A}/\mu\text{s}$ , $T_{j\text{max}}=150^\circ\text{C}$	dv/dt	-6	kV/ $\mu\text{s}$
Gate source voltage	$V_{GS}$	$\pm 12$	V
Power dissipation $T_A=25^\circ\text{C}$	$P_{\text{tot}}$	0.25	W
Operating and storage temperature	$T_j$ , $T_{\text{stg}}$	-55... +150	$^\circ\text{C}$
IEC climatic category; DIN IEC 68-1		55/150/56	
ESD Class JESD22-A114-HBM		Class 0	

**Thermal Characteristics**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Thermal resistance, junction - soldering point	$R_{thJS}$	-	-	180	K/W
Thermal resistance, junction - ambient, leaded	$R_{thJA}$	-	-	500	

**Electrical Characteristics**, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Drain-source breakdown voltage $V_{GS}=0, I_D=-250\mu A$	$V_{(BR)DSS}$	-20	-	-	V
Gate threshold voltage, $V_{GS} = V_{DS}$ $I_D=-1.5\mu A$	$V_{GS(th)}$	-0.6	-0.9	-1.2	
Zero gate voltage drain current $V_{DS}=-20V, V_{GS}=0, T_j=25^{\circ}C$ $V_{DS}=-20V, V_{GS}=0, T_j=150^{\circ}C$	$I_{DSS}$	- -	-0.1 -10	-1 -100	$\mu A$
Gate-source leakage current $V_{GS}=-12V, V_{DS}=0$	$I_{GSS}$	-	-10	-100	
Drain-source on-state resistance $V_{GS}=-2.5V, I_D=-0.29A$	$R_{DS(on)}$	-	1.27	2.1	$\Omega$
Drain-source on-state resistance $V_{GS}=-4.5, I_D=-0.39A$	$R_{DS(on)}$	-	0.7	1.2	

**Electrical Characteristics**, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

### Dynamic Characteristics

Transconductance	$g_{fs}$	$ V_{DS}  \geq 2 \cdot  I_D  \cdot R_{DS(on)max}$ $I_D = -0.31\text{A}$	0.35	0.7	-	S
Input capacitance	$C_{iss}$	$V_{GS}=0, V_{DS}=-15\text{V},$ $f=1\text{MHz}$	-	45	56	pF
Output capacitance	$C_{oss}$		-	21	26	
Reverse transfer capacitance	$C_{rss}$		-	17	22	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=-10\text{V}, V_{GS}=-4.5\text{V},$ $I_D=-0.39\text{A}, R_G=6\Omega$	-	3.8	5.7	ns
Rise time	$t_r$		-	5	7.5	
Turn-off delay time	$t_{d(off)}$		-	5.1	7.6	
Fall time	$t_f$		-	3.2	4.8	

### Gate Charge Characteristics

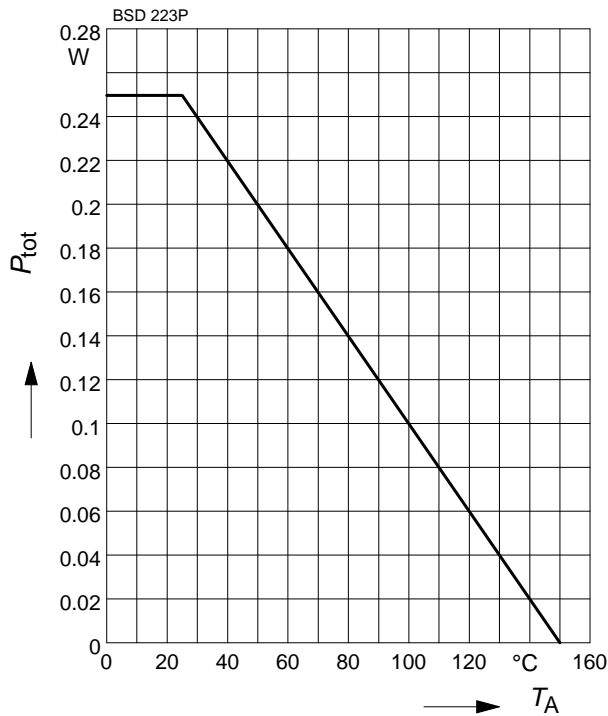
Gate to source charge	$Q_{gs}$	$V_{DD}=-10\text{V}, I_D=-0.39\text{A}$	-	-0.04	-0.05	nC
Gate to drain charge	$Q_{gd}$		-	-0.4	-0.5	
Gate charge total	$Q_g$	$V_{DD}=-10\text{V}, I_D=-0.39\text{A},$ $V_{GS}=0 \text{ to } -4.5\text{V}$	-	-0.5	-0.62	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD}=-10\text{V}, I_D=-0.39\text{A}$	-	-2.2	-2.7	V

### Reverse Diode

Inverse diode continuous forward current	$I_S$	$T_A=25^\circ\text{C}$	-	-	-0.39	A
Inv. diode direct current, pulsed	$I_{SM}$		-	-	-1.56	
Inverse diode forward voltage	$V_{SD}$	$V_{GS}=0, I_F=-0.39$	-	-1	-1.33	V
Reverse recovery time	$t_{rr}$	$V_R=-10\text{V},  I_F  =  I_D ,$ $di_F/dt=100\text{A}/\mu\text{s}$	-	7.6	9.5	ns
Reverse recovery charge	$Q_{rr}$		-	1.1	1.4	nC

### 1 Power dissipation

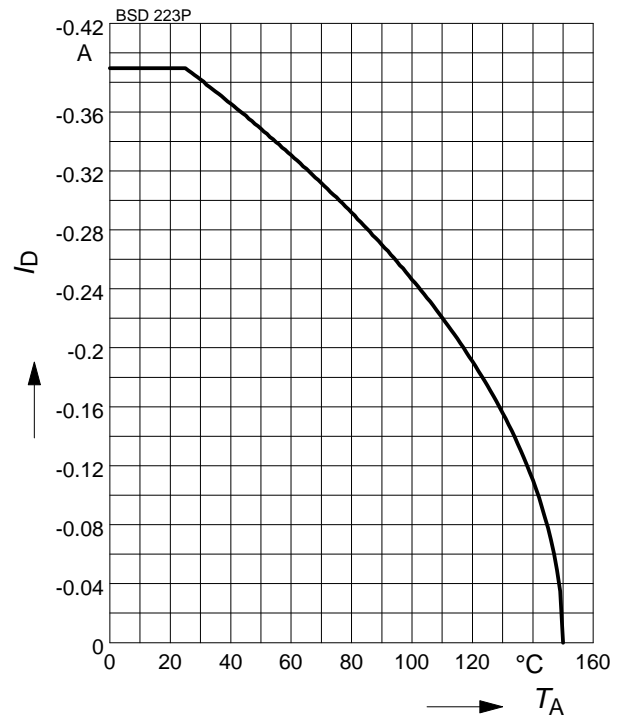
$$P_{\text{tot}} = f(T_A)$$



### 2 Drain current

$$I_D = f(T_A)$$

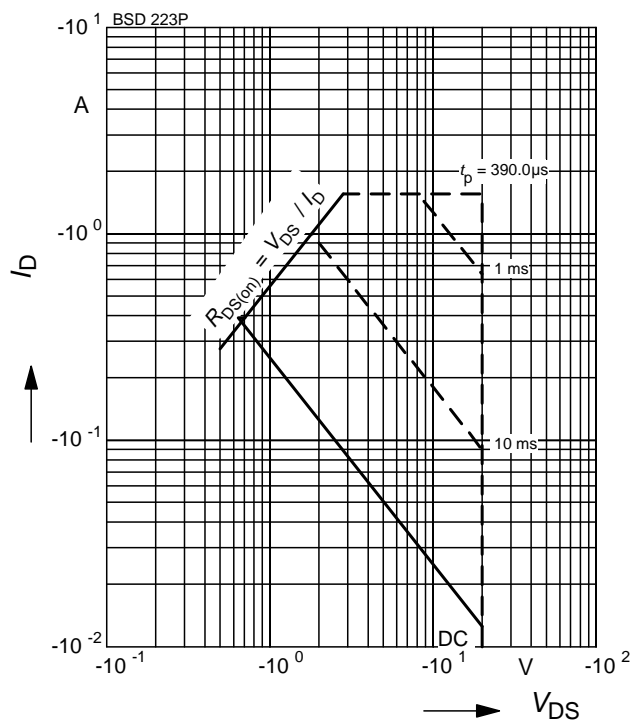
parameter:  $|V_{GS}| \geq 4.5 \text{ V}$



### 3 Safe operating area

$$I_D = f(V_{DS})$$

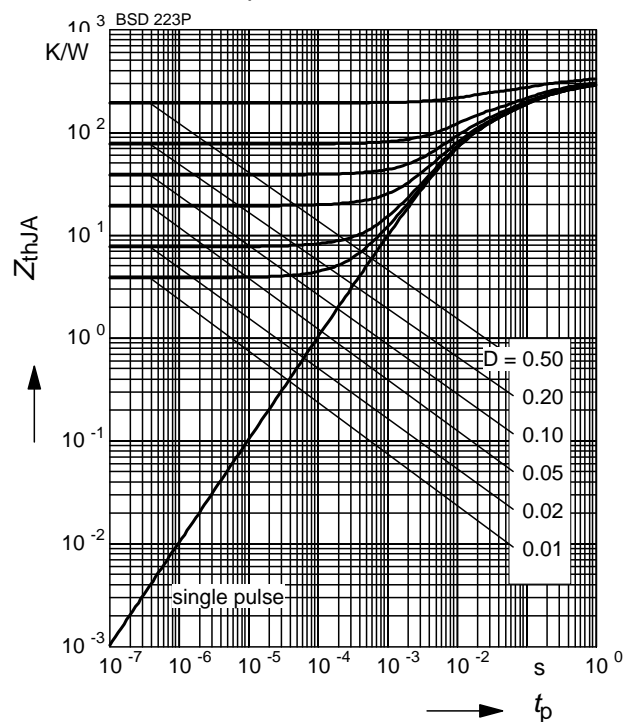
parameter:  $D = 0$ ,  $T_A = 25^\circ\text{C}$



### 4 Transient thermal impedance

$$Z_{\text{thJA}} = f(t_p)$$

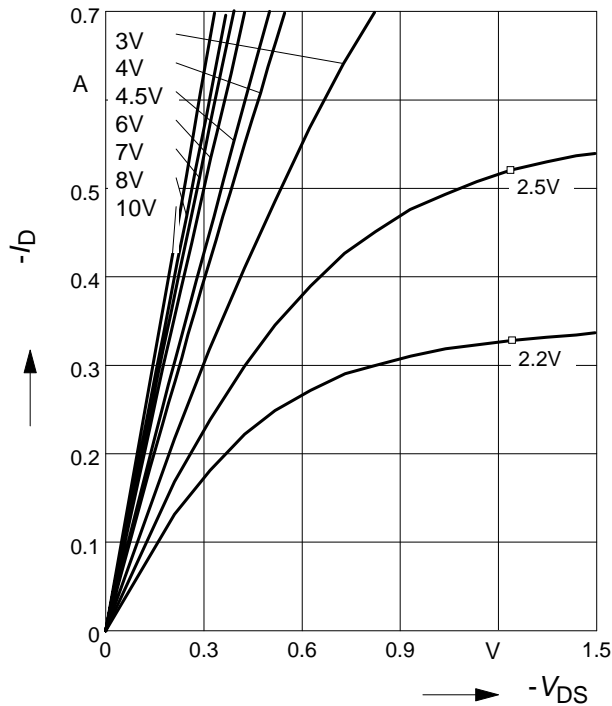
parameter:  $D = t_p/T$



**5 Typ. output characteristic**

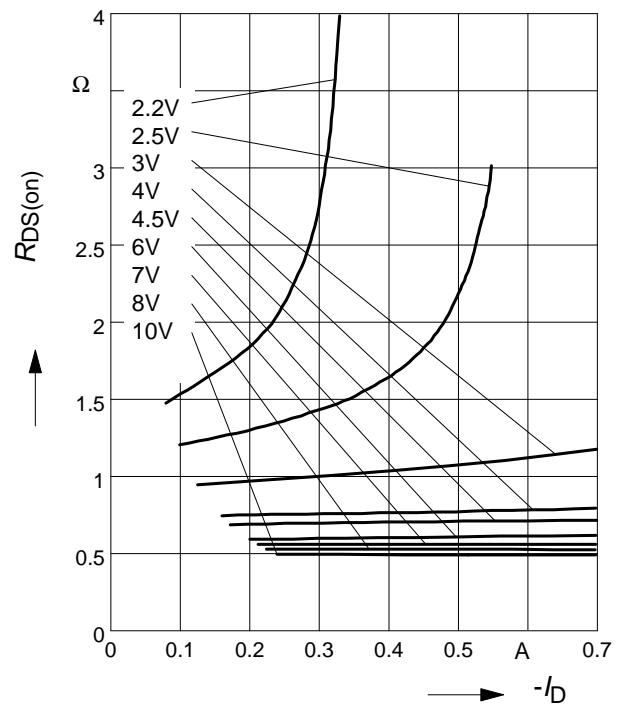
$$I_D = f(V_{DS})$$

parameter:  $T_j = 25^\circ\text{C}$


**6 Typ. drain-source on resistance**

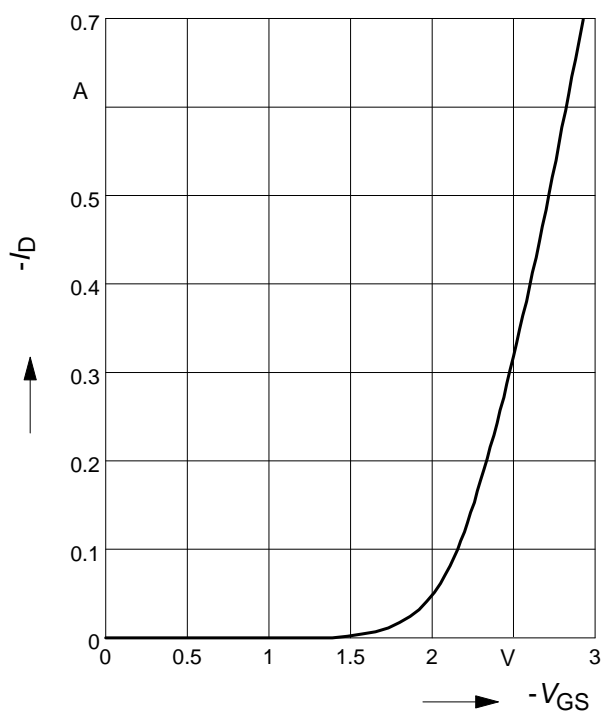
$$R_{DS(on)} = f(I_D)$$

parameter:  $V_{GS}$


**7 Typ. transfer characteristics**

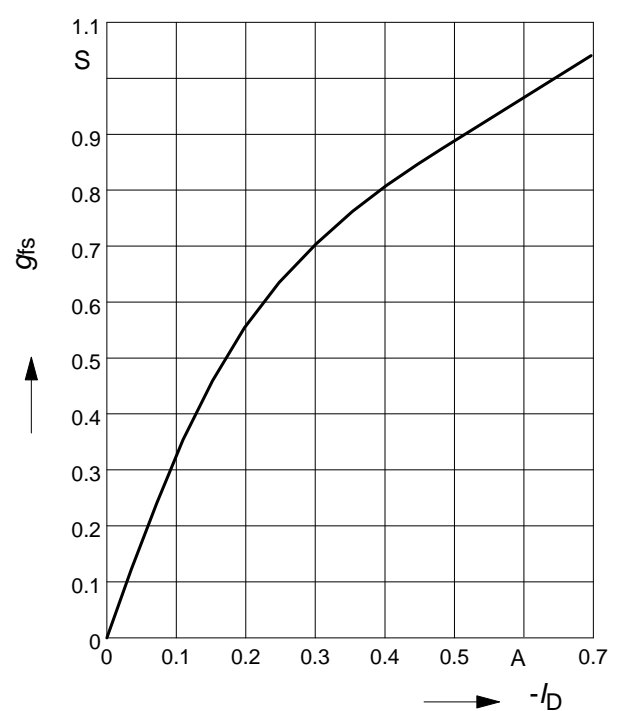
$$I_D = f(V_{GS}); |V_{DS}| \geq 2 \times |I_D| \times R_{DS(on)max}$$

parameter:  $T_j = 25^\circ\text{C}$


**8 Typ. forward transconductance**

$$g_{fs} = f(I_D)$$

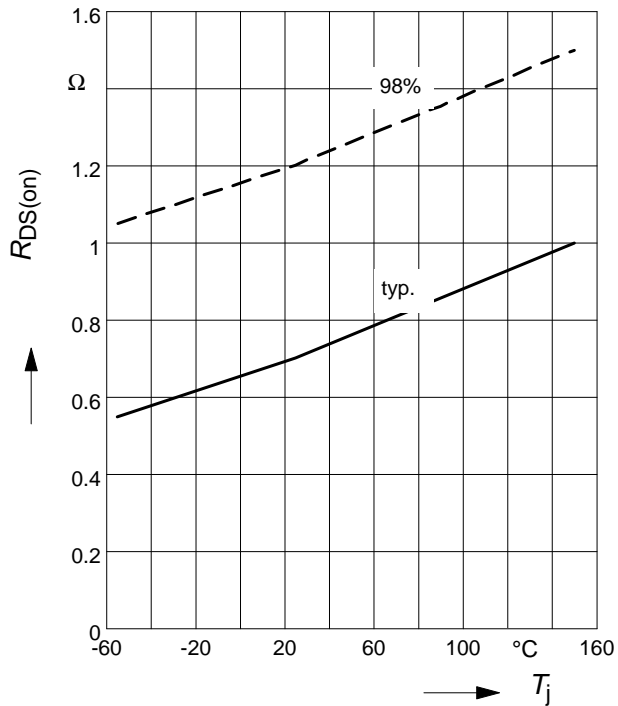
parameter:  $T_j = 25^\circ\text{C}$



### 9 Drain-source on-resistance

$$R_{DS(on)} = f(T_j)$$

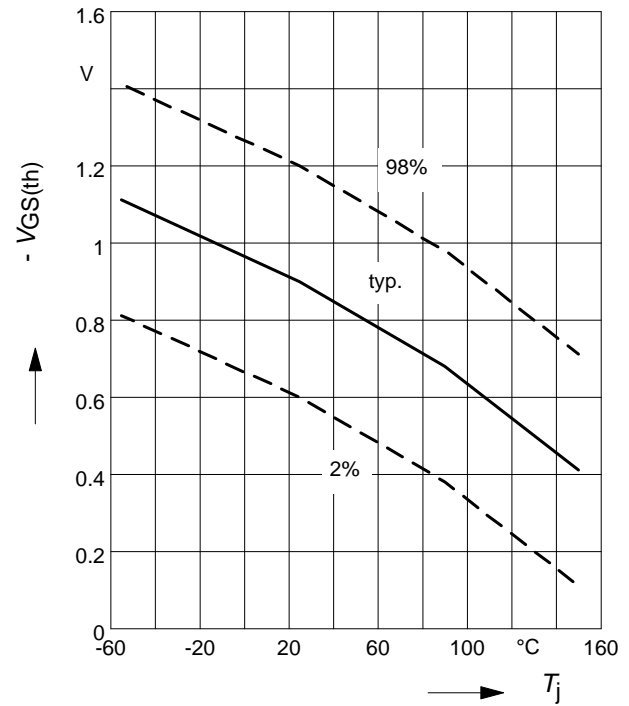
parameter:  $I_D = -0.39 \text{ A}$ ,  $V_{GS} = -4.5 \text{ V}$



### 10 Typ. gate threshold voltage

$$V_{GS(th)} = f(T_j)$$

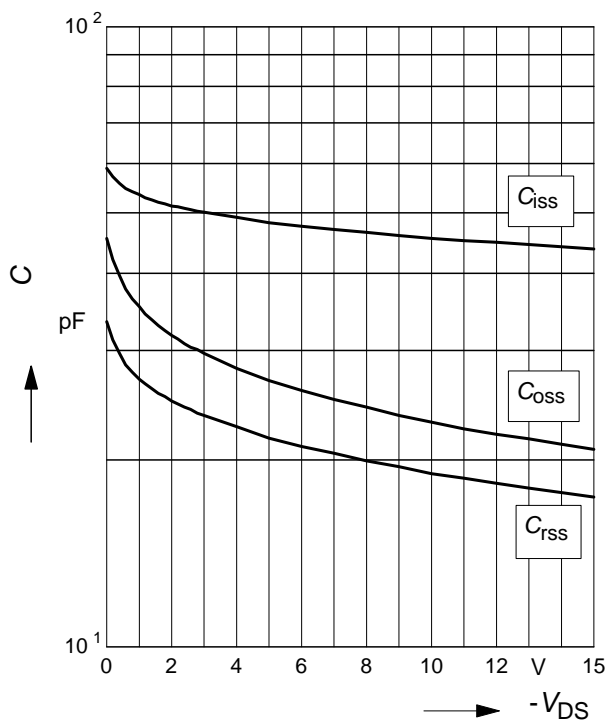
parameter:  $V_{GS} = V_{DS}$



### 11 Typ. capacitances

$$C = f(V_{DS})$$

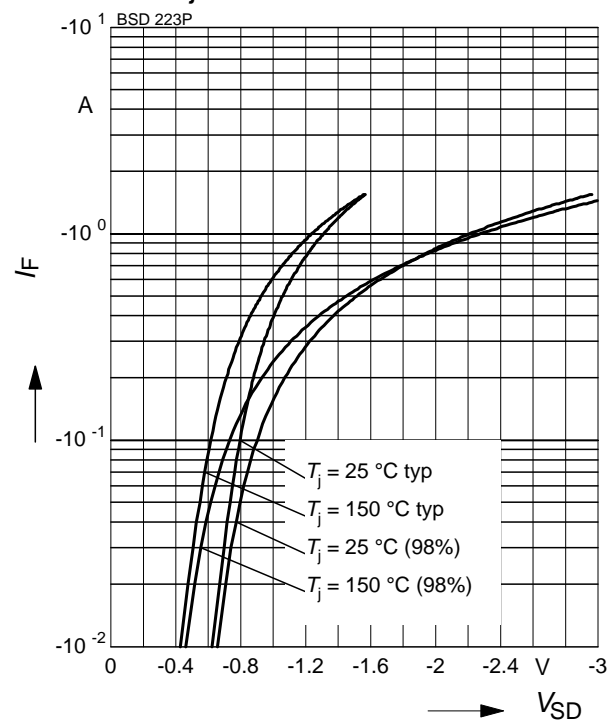
parameter:  $V_{GS}=0$ ,  $f=1 \text{ MHz}$



### 12 Forward character. of reverse diode

$$I_F = f(V_{SD})$$

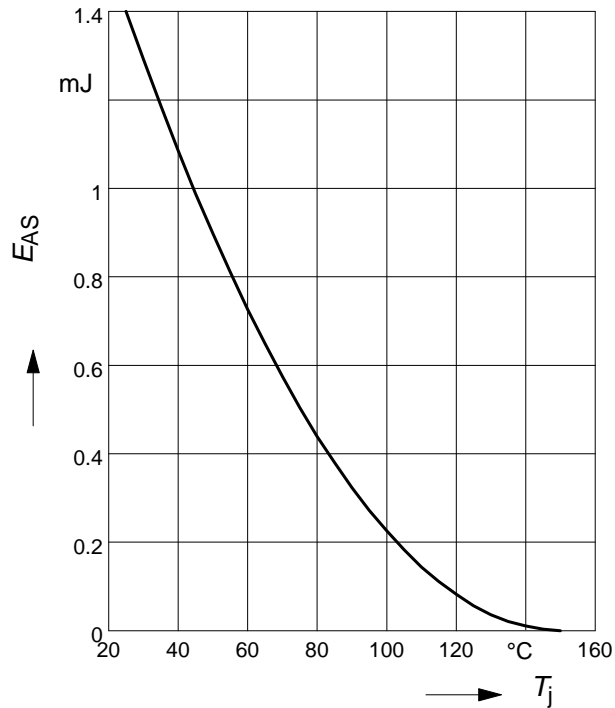
parameter:  $T_j$



**13 Typ. avalanche energy**

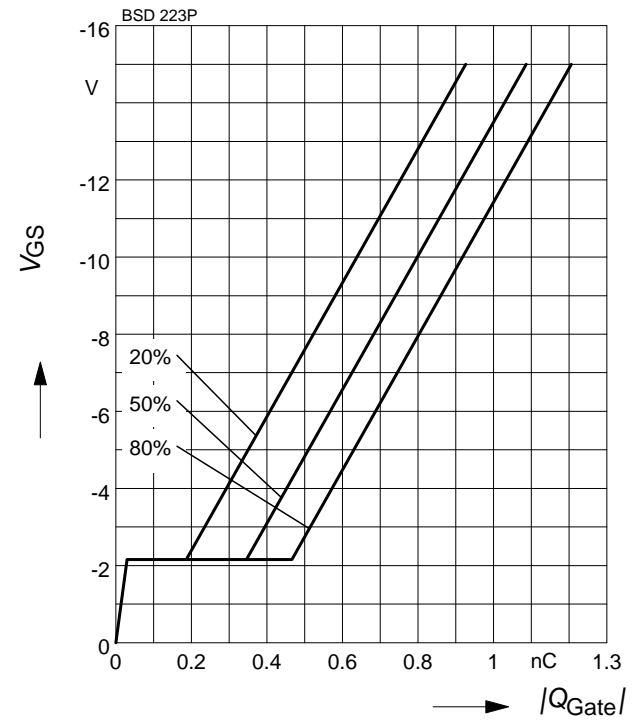
$$E_{AS} = f(T_j), \text{ par.: } I_D = -0.39 \text{ A}$$

$$V_{DD} = -10 \text{ V}, R_{GS} = 25 \Omega$$

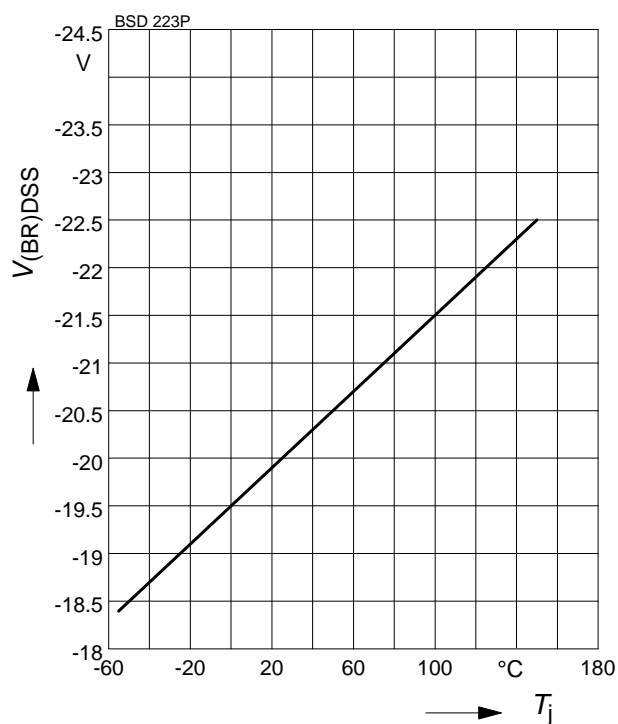

**14 Typ. gate charge**

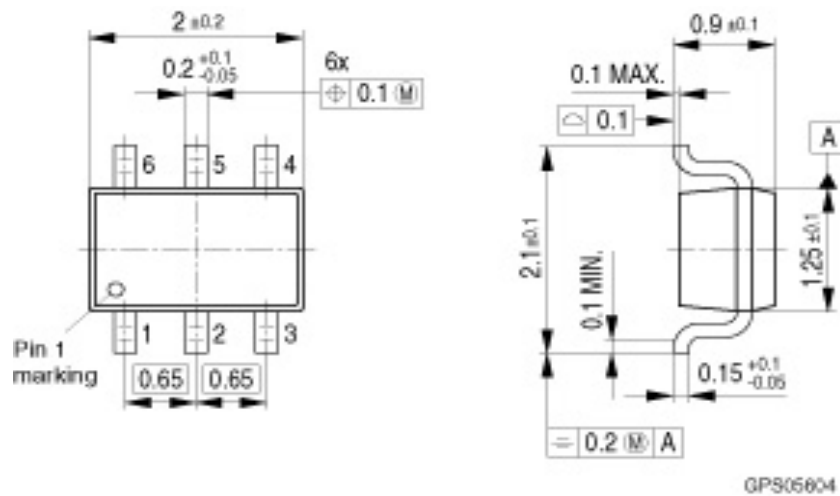
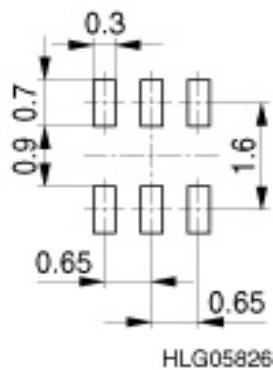
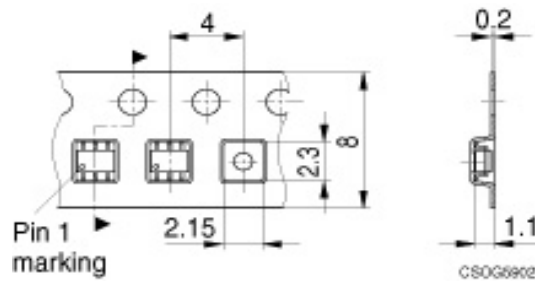
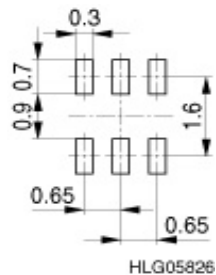
$$V_{GS} = f(Q_{Gate})$$

$$\text{parameter: } I_D = -0.39 \text{ A pulsed; } T_j = 25^\circ\text{C}$$


**15 Drain-source breakdown voltage**

$$V_{(BR)DSS} = f(T_j)$$



**Package Outline:**

**Footprint:**

**Packaging:**

**Reflow soldering:**


Dimensions in mm

**For symmetric types there is no defined Pin 1 orientation in the reel.**



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